

**IN THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (currently amended) A modeling compound comprising, in combination,  
polyvinyl chloride resin;  
primary plasticizer;  
epoxidized soybean oil secondary plasticizer stabilizer;  
a heat stabilizer comprising zinc;  
dry expanded microspheres;  
glass microspheres; and  
rheology modifier, wherein the modeling compound comprises .3% or less of water.
2. (canceled)
3. (original) A modeling compound as in claim 1 where said primary plasticizer comprises a monomeric plasticizer.
4. (original) A modeling compound as in claim 1 where said primary plasticizer comprises a polymeric plasticizer.
5. (currently amended) A modeling compound as in claim 1 where said zinc heat stabilizer ~~comprises metal ion which complexes with HCL~~.
6. (canceled)
7. (original) A modeling compound as in claim 1 where said rheology modifier comprises a thixotropic agent.

8. (original) A modeling compound as in claim 1 further comprising a secondary plasticizer.

9. (currently amended) A modeling compound comprising, in combination,  
40% - 60% polyvinyl chloride by weight of the compound;  
20% - 25% primary plasticizer by weight of the compound;  
1% - 3% epoxidized soybean oil secondary plasticizer by weight of the compound;  
1% - 2% zinc stabilizer by weight of the compound;  
15% - 25% dry expanded microspheres and glass microspheres by weight of the compound; and  
1% - 3% thixotropic agent by weight of the compound, wherein the modeling compound comprises 0.3% or less of water.

10. (original) A modeling compound as in claim 9 where said polyvinyl chloride comprises 48.8% by weight of the compound.

11. (original) A modeling compound as in claim 9 where said primary plasticizer comprises a monomeric plasticizer.

12. (original) A modeling compound as in claim 9 where said primary plasticizer comprises a polymeric plasticizer.

13. (original) A modeling compound as in claim 9 where said primary plasticizer comprises 20.7% by weight of the compound.

14. (currently amended) A modeling compound as in claim 9 where said epoxidized soybean oil secondary plasticizer comprises 1.2% by weight of the compound.

15. (currently amended) A modeling compound as in claim 9 where said zinc stabilizer comprises metal ion which complexes with HCL.
16. (currently amended) A modeling compound as in claim 9 where said zinc stabilizer comprises 1.2% by weight of the compound.
17. (canceled)
18. (original) A modeling compound as in claim 9 where said microspheres comprise 26.4% by weight of the compound.
19. (original) A modeling compound as in claim 9 where said thixotropic agent comprises 1.8% by weight of the compound.
20. (currently amended) A process for forming a modeling compound, comprising,  
mixing a polyvinyl chloride resin, a primary plasticizer, a secondary plasticizer and a stabilizer to a smooth liquid consistency to create a mixture;  
~~adding and mixing microspheres to said mixture after said smooth liquid consistency is achieved; and~~  
~~adding rheology modifier after said microspheres are mixed with said mixture; and~~  
~~thereafter adding and mixing microspheres to said mixture.~~
21. (canceled)
22. (original) A process for forming a modeling compound as in claim 20 where said primary plasticizer comprises a monomeric plasticizer.
23. (original) A process for forming a modeling compound as in claim 20 where said primary plasticizer comprises a polymeric plasticizer.

24. (original) A process for forming a modeling compound as in claim 20 where said stabilizer comprises metal ions which complex with HCL.
25. (original) A process for forming a modeling compound as in claim 20 where said rheology modifier comprises a thixotropic agent.
26. (original) A process for forming a modeling compound as in claim 21 where said polyvinyl chloride comprises 40% - 60% by weight of the compound.
27. (original) A process for forming a modeling compound as in claim 20 where said primary plasticizer comprises 20% - 25% by weight of the compound.
28. (original) A process for forming a modeling compound as in claim 20 where said secondary plasticizer comprises 1% - 3% by weight of the compound.
29. (original) A process for forming a modeling compound as in claim 24 where said stabilizer comprises 1% - 2% by weight of the compound.
30. (original) A process for forming a modeling compound as in claim 25 where said thixotropic agent comprises 1% - 3% by weight of the compound.
31. (new) The modeling compound of claim 1, wherein the primary plasticizer is acetyltributyl citrate.
32. (new) The modeling compound of claim 1, wherein the rheology buffer is an organophilic clay.

33. (new) The modeling compound of claim 1, wherein the heat stabilizer comprising zinc is calcium zinc.
34. (new) The modeling compound of claim 7, wherein the thixotropic agent is an organophilic clay.
35. (new) The modeling compound of claim 9, wherein the zinc stabilizer is calcium zinc.
36. (new) The modeling compound of claim 15, wherein the zinc stabilizer is calcium zinc.
37. (new) The modeling compound of claim 16, wherein the zinc stabilizer is calcium zinc.
38. (new) The modeling compound of claim 25, wherein the thixotropic agent is an organophilic clay.
39. (new) The modeling compound of claim 9, wherein the primary plasticizer is acetyltributyl citrate.